Silicon N-Channel/P-Channel Power MOS FET Array

HITACHI

Application

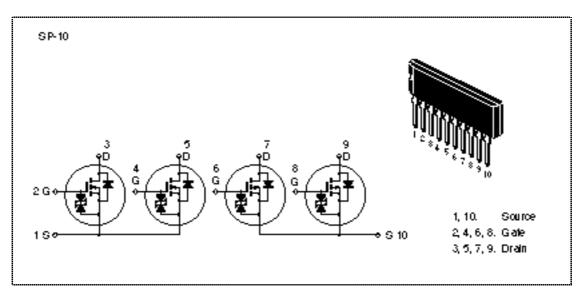
High speed power switching

Features

- Low on-resistance N-channel: $R_{DS(on)}$ 0.17 , $V_{GS} = 10$ V, $I_D = 2.5$ A P-channel: $R_{DS(on)}$ 0.2 , $V_{GS} = -10$ V, $I_D = -2.5$ A
- Capable of 4 V gate drive
- Low drive current
- High speed switching
- High density mounting
- Suitable for H-bridged motor driver



Outline



Absolute Maximum Ratings (Ta = 25°C) (1 Unit)

		Rating			
ltem	Symbol	Nch	Pch	Unit	
Drain to source voltage	V _{DSS}	60	-60	V	
Gate to source voltage	V _{GSS}	±20	±20	V	
Drain current	ID	5	-5	A	
Drain peak current	I _{D(pulse)} *1	20	-20	A	
Body to drain diode reverse drain current	I _{DR}	5	-5	A	
Channel dissipation	Pch (Tc = 25°C	;)* ² 28		W	
Channel dissipation	Pch* ²	4		W	
Channel temperature	Tch	150		°C	
Storage temperature	Tstg	-55 to +150		°C	

Notes: 1. PW 10 µs, duty cycle 1%

2. 4 Devices operation

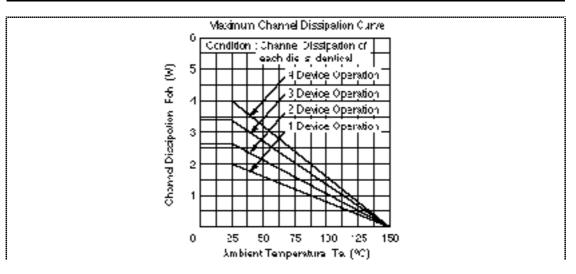


Electrical Characteristics (Ta = 25°C) (1 Unit)

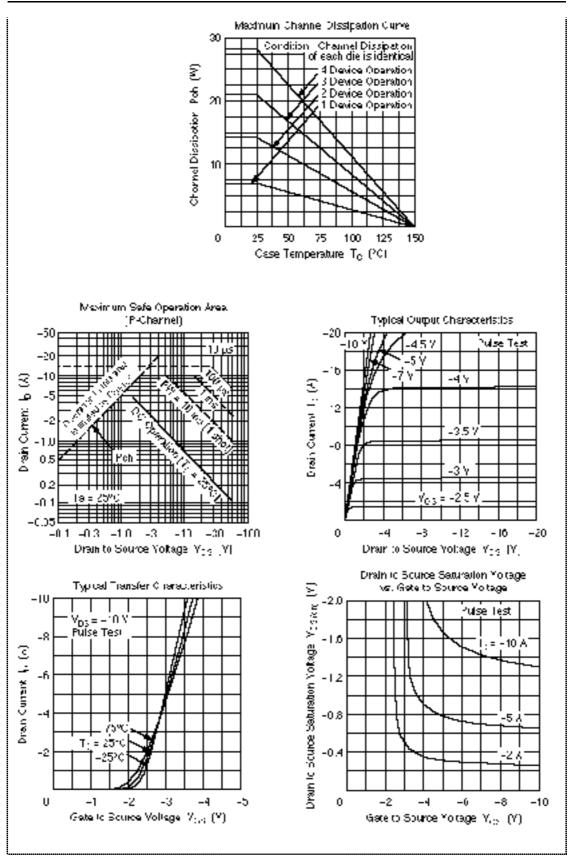
		N cha	annel		P channel				
Item	Symbol	Min	Тур	Max	Min	Тур	Max	Unit	Test conditions
Drain to source breakdown voltage	V _(BR) DS S	60	_	—	-60	—	_	V	$I_{D} = 10 \text{ mA}, V_{GS} = 0$
Gate to source breakdown voltage	V _(BR) GS S	±20	—	—	±20	—	—	V	I _G = ±100 μA, V _{DS} = 0
Gate to source leak current	IGSS	—	—	±10	—	—	±10	μA	$V_{GS} = \pm 16 \text{ V}, \text{ V}_{DS} = 0$
Zero gate voltage drain current	IDSS	—	—	250	—	—	-250	μA	$V_{DS} = 50 \text{ V}, \text{ V}_{GS} = 0$
Gate to source cutoff voltage	VGS(off)	1.0	—	2.0	-1.0	—	-2.0	V	I _D = 1 mA, V _{DS} = 10 V
Static drain to source on state resistance	R _{DS(on)}		0.13	0.17	—	0.15	0.2		I _D = 2.5 A, V _{GS} = 10 V ^{*1}
		—	0.18	0.24	—	0.20	0.27		I _D = 2.5 A, V _{GS} = 4 V*1
Forward transfer admittance	y _{fs}	2.7	4.5	—	2.7	5.0	—	S	I _D = 2.5 A, V _{DS} = 10 V ^{*1}
Input capacitance	Ciss	—	400	—	—	900		pF	$V_{DS} = 10 V, V_{GS} = 0,$
Output capacitance	Coss		220		—	460		pF	f = 1 MHz
Reverse transfer capacitance	Crss	—	60	—	—	130	—	pF	
Turn-on delay time	^t d(on)	—	5	—	—	8	—	ns	I _D = 2.5 A, V _{GS} = 10 V,
Rise time	t _r	—	30	—	—	35	—	ns	R _L = 12
Turn-off delay time	^t d(off)		170	—	—	180		ns	
Fall time	t _f		75	—	—	85		ns	
Body to drain diode forward voltage	V _{DF}	—	1.0	—	—	-1.0	—	V	I _F = 5 A, V _{GS} = 0
Body to drain diode reverse recovery time	t _{rr}		100		—	170		μs	$I_F = 5 \text{ A}, V_{GS} = 0,$ dIF/dt = 50 A/µs

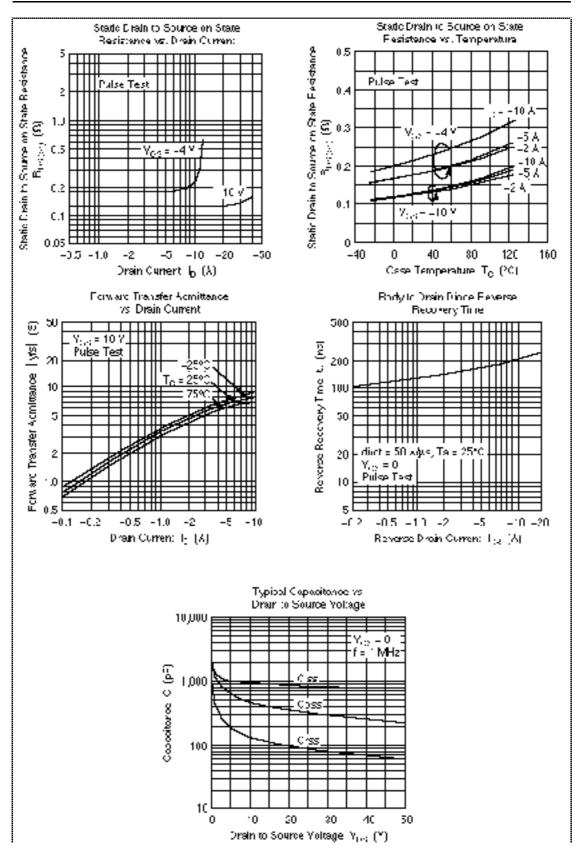
Note: 1. Pulse Test

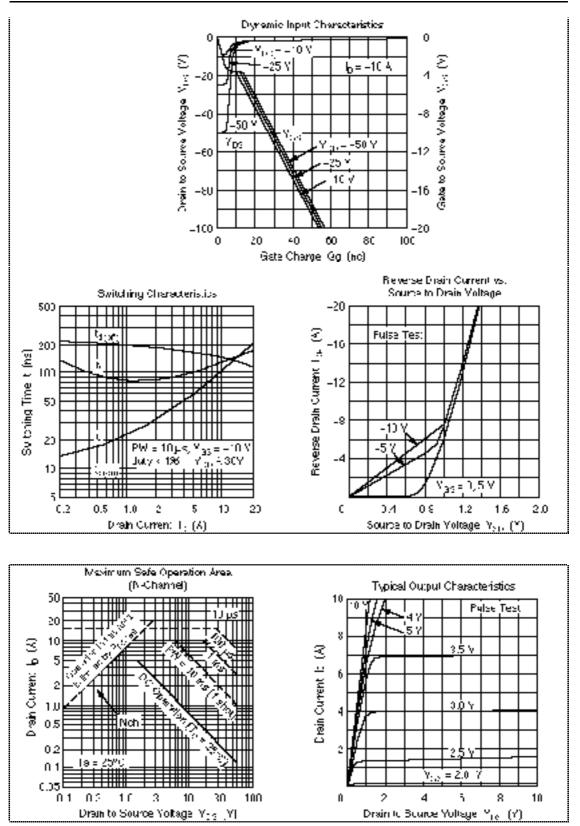
Polarity of test conditions for P channel device is reversed.

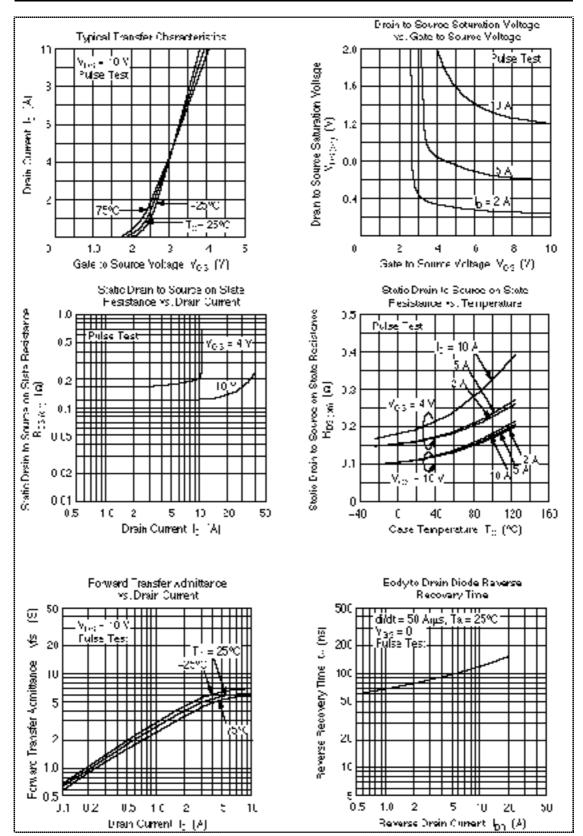


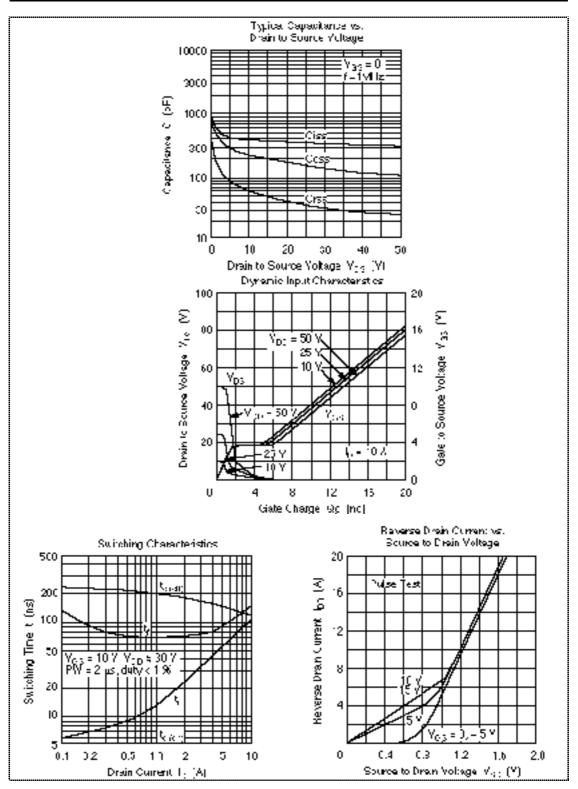












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